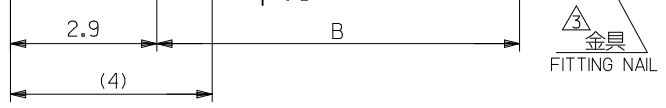
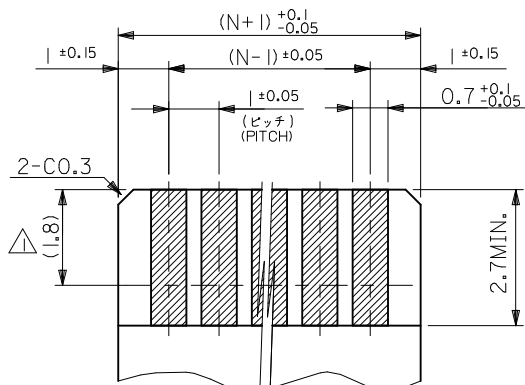


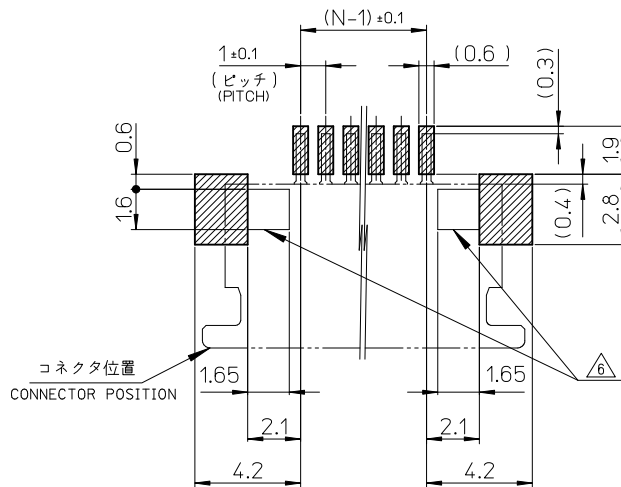
35	31.2	29	52271-3069	30
34	30.2	28	52271-2969	29
33	29.2	27	52271-2869	28
32	28.2	26	52271-2769	27
31	27.2	25	52271-2669	26
30	26.2	24	52271-2569	25
29	25.2	23	52271-2469	24
28	24.2	22	52271-2369	23
27	23.2	21	52271-2269	22
26	22.2	20	52271-2169	21
25	21.2	19	52271-2069	20
24	20.2	18	52271-1969	19
23	19.2	17	52271-1869	18
22	18.2	16	52271-1769	17
21	17.2	15	52271-1669	16
20	16.2	14	52271-1569	15
19	15.2	13	52271-1469	14
18	14.2	12	52271-1369	13
17	13.2	11	52271-1269	12
16	12.2	10	52271-1169	11
15	11.2	9	52271-1069	10
14	10.2	8	52271-0969	9
13	9.2	7	52271-0869	8
12	8.2	6	52271-0769	7
11	7.2	5	52271-0669	6
10	6.2	4	52271-0569	5
9	5.2	3	52271-0469	4
C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CIRCUITS
52271-**-29			CONNECTOR SERIES NO.	



REVISED EC NO.: J2012-1390 DRWN:KNAGUMO 2012/05/10 CH'KD:KAKAHASHI 2012/05/10 APPR:KMORIKAWA 2012/05/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	TITLE 1.0 FPC CONN ZIF SMT (BOTTOM CONTACT) -LEAD FREE- molex DOCUMENT NO. SD-52271-038 SHEET NO. 1 OF 2
	10 UNDER ±0.2		MM ONLY	10:1	METRIC	
	10 OVER 30 UNDER ±0.25		DRAWN BY	DATE		
	30 OVER ±0.3		M.UMEDA	2005/03/08		
	ANGULAR ±3 °		CHECKED BY	DATE		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		K.TOYODA	2005/03/08		
			APPROVED BY	DATE		
			N.UKITA	2005/03/08		
			MATERIAL NO.			
			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
			A3			



(仕上り厚さ: 0.3±0.05)
(THICKNESS: 0.3±0.05)
適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(SCALE 10:1)



参考基板レイアウト
RECOMMENDED PCB
PATTERN DIMENSIONS(REF.)
(SCALE 5:1)

注記 NOTES

- △1 接点部までの嵌合長さ。
LENGTH TO CONTACT POINT.
- 2. 使用材料 MATERIAL
 - ハウジング : 46 NYLON, UL94V-0
HOUSING
 - アクチュエータ : PPS, UL94V-0
ACTUATOR
 - ターミナル : リン青銅 (t=0.25)
TERMINAL PHOSPHOR BRONZE (t=0.25)
 - メッキ : 接点部:金メッキ : 0.1 MICROMETER MIN.
CONTACT PORTION : GOLD PLATING : 0.1 MICROMETER MIN.
半田付部:錫メッキ : 1.0 MICROMETER MIN.
SOLDERING PORTION : TIN PLATING : 1.0 MICROMETER MIN.
下地:ニッケルメッキ : 1.0 MICROMETER MIN.
UNDER PLATING : NICKEL PLATING : 1.0 MICROMETER MIN.
 - 金具 : 銅合金 (t=0.25)
FITTING NAIL CAPPER ALLOY (t=0.25)
 - メッキ:錫メッキ : 1.0 MICROMETER MIN.
PLATING : TIN PLATING : 1.0 MICROMETER MIN.
 - 下地:ニッケルメッキ : 1.0 MICROMETER MIN.
UNDER PLATING : NICKEL PLATING : 1.0 MICROMETER MIN.

- △3 パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING
OF P.C.B. PATTERN.
- 4. エンボステーブ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO.54550-***29 SHOULD BE LOCKED.
- △5 テール及び金具の平坦度は、0.15以下とする。
TAIL AND NAIL COPLANRITY TO BE 0.15 MAXIMUM.
- △6 パターン書き込み禁止エリア
NO FOOT PRINT AREA.

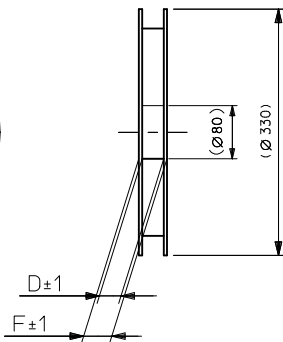
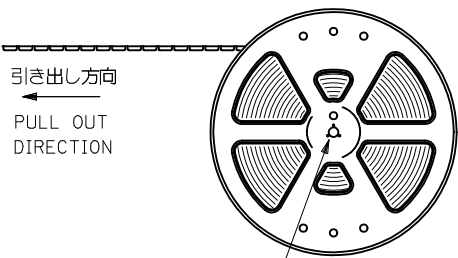
FPC について :

打抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は、熱硬化接着剤を推奨致します。

ABOUT FPC :

RECOMMENDED PUNCHER DIRECTION :
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO. J2012-1390 DRWN:KNAGUMO 2012/05/10 CHKD:KAKAHASHI 2012/05/10 APP:KMORIKAWA 2012/05/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M.UMEDA	DATE 2005/03/08	TITLE 1.0 FPC CONN ZIF SMT (BOTTOM CONTACT) -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY K.TOYODA	DATE 2005/03/08		
	30 OVER	±0.3	APPROVED BY N.UKITA	DATE 2005/03/08		
ANGULAR	±3 °	MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-52271-038	SHEET NO. 2 OF 2		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

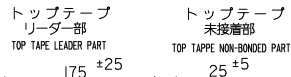


NOTES

1. 製品番号 52271-**29 の梱包状態はアクチュエータがロックした状態とする。
詳細寸法については 図面 SD-52271-038 を参照下さい。
IN THE PACKAGE, AUTUATOR OF PART NO. 52271-**29 SHOULD BE LOCKED
RE DETAILED DIMENSIONS, SEE SD-52271-038.

2. 梱包数量：1000個/リール
NUMBER OF CONNECTORS : 1000 PCS/REEL

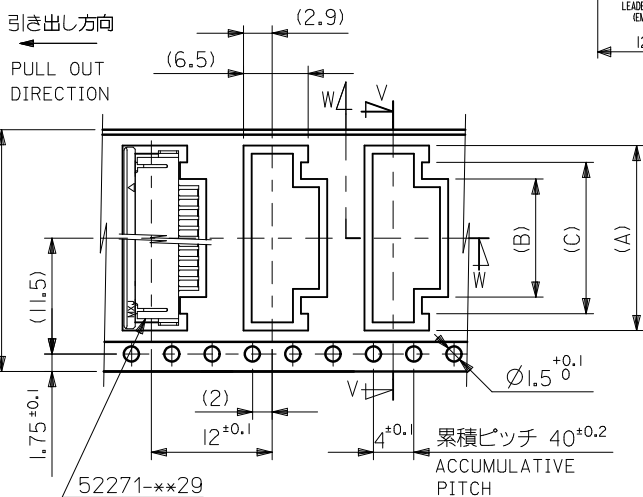
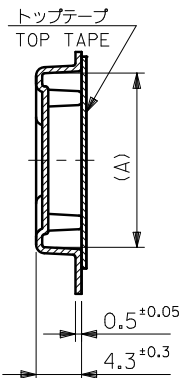
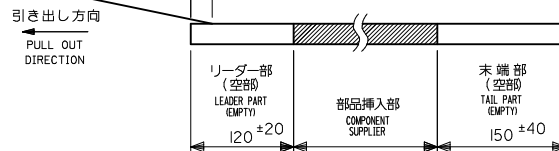
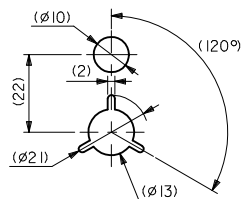
3. リードテープ長さ LEAD TAPE LENGTH



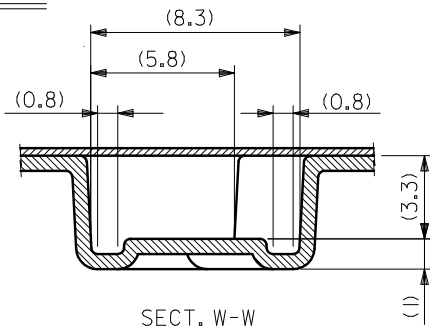
4. カバーテープの剥離強度については、IEC60286-3に準拠
COVER TAPE PEEL FORCE IS DEFINED BY IEC60286-3

5. 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)
トップテープ (TOPTAPE): PET, PE, PEF
リール (REEL): ポリスチレン (PS) <リサイクル材を含む>
POLYSTYREN (PS) <RECYCLE MATERIAL CONTAINED>

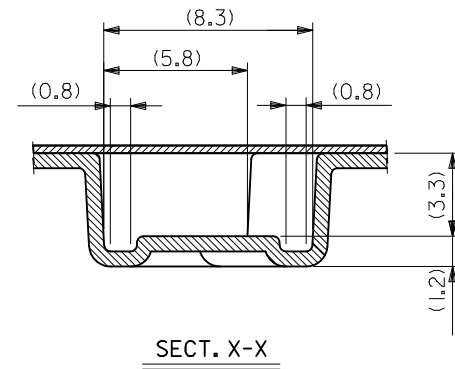
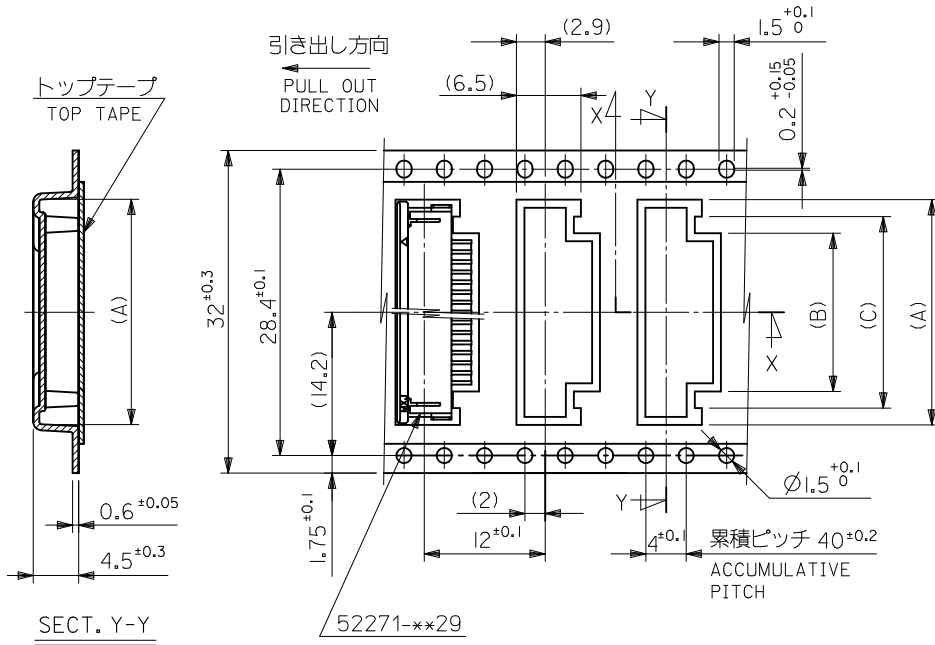
6. 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.



24	29.4	25.4	15	11.4	18.3	52271-1169	11
			14	10.4	17.3	52271-1069	10
			12	8.4	15.3	52271-0869	8
			11	7.4	14.3	52271-0769	7
			10	6.4	13.3	52271-0669	6
			9	5.4	12.3	52271-0569	5
			8	4.4	11.3	52271-0469	4
			キャリアテープ幅 CARRIER TAPE WIDTH			F	D

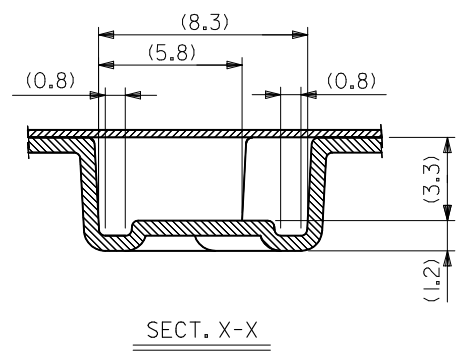
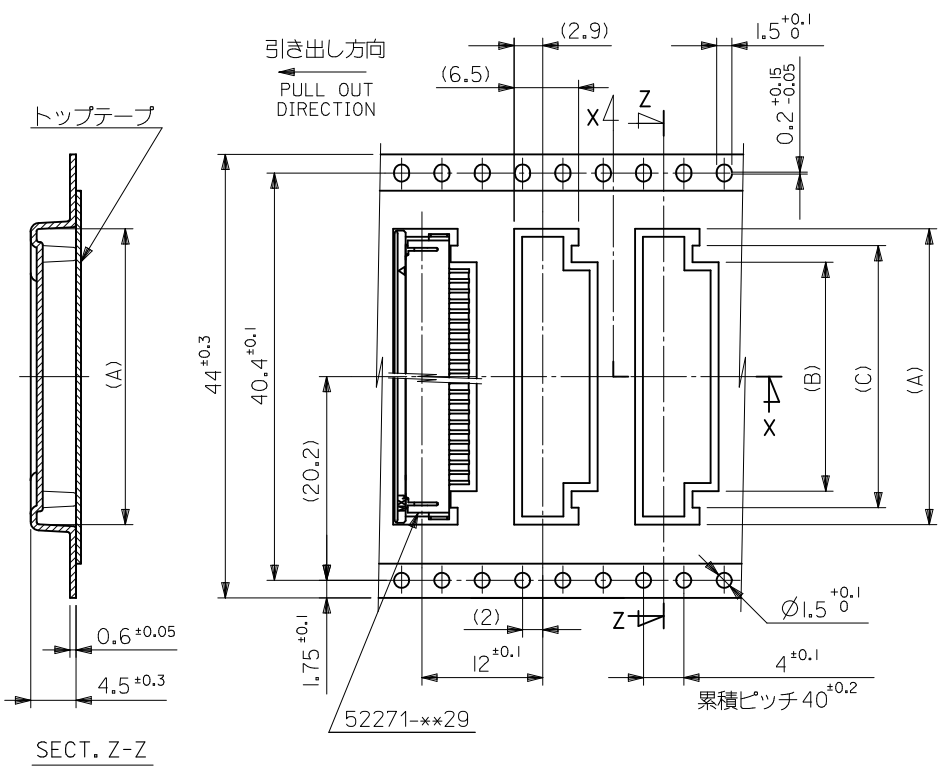


REVISED EC NO: J2010-2474 DRWN: YUHASEGAWA 2010/06/08 CHKD: K. TOYODA 2010/06/08 APPR: KMORI KAWA 2010/06/09	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		MODEL NO. 52271-**69	
		10 UNDER	±0.2	DRAWN BY M. UEDA	DATE 2005/03/08	TITLE EMBOSSD TAPE PACKAGE FOR 52271-**29 -LEAD FREE-					
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOYODA	DATE 2005/03/08	MOLEX INCORPORATED DOCUMENT NO. SD-52271-039 SHEET NO. 1 OF 4					
		30 OVER	±0.3	APPROVED BY N. UKITA	DATE 2005/03/08						
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



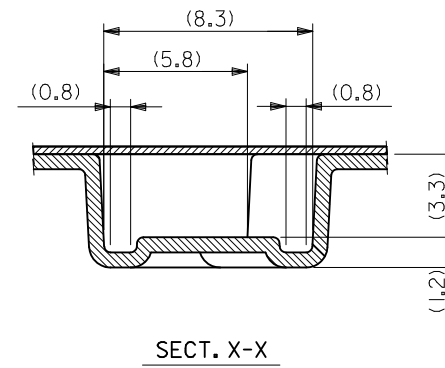
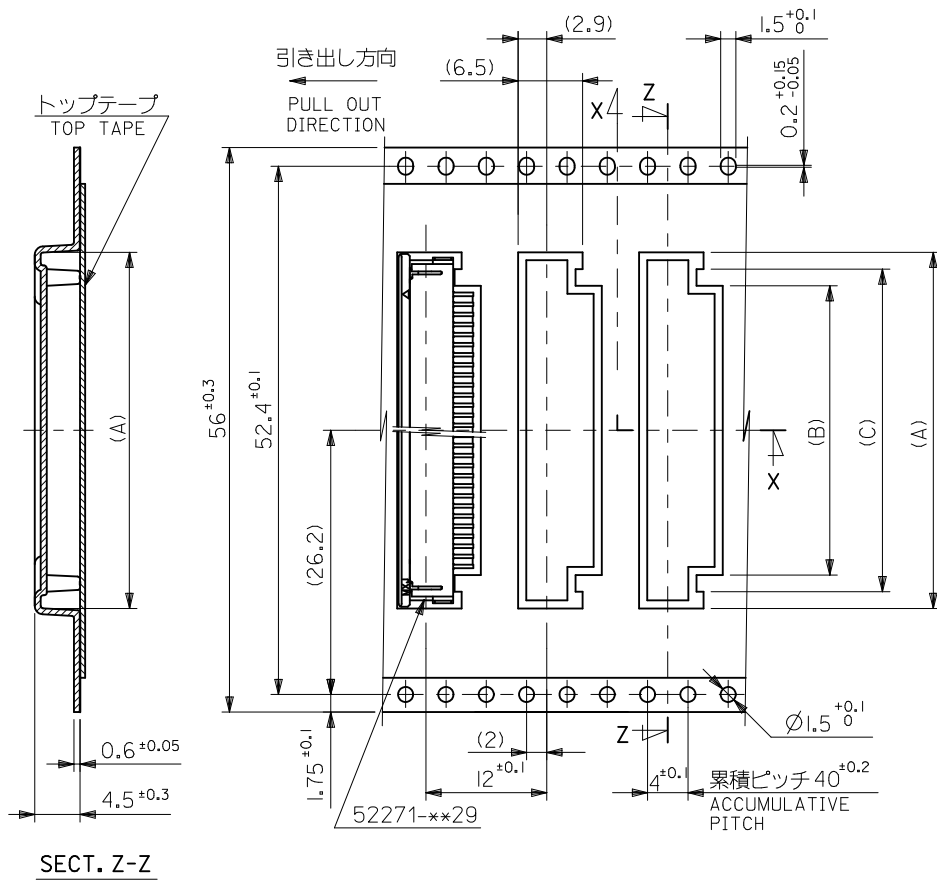
32	37.4	33.4	20	16.4	23.35	52271-1669	16		
			19	15.4	22.35	52271-1569	15		
			18	14.4	21.35	52271-1469	14		
			17	13.4	20.35	52271-1369	13		
			16	12.4	19.35	52271-1269	12		
キャリアテープ幅 CARRIER TAPE WIDTH			F	D	(C)	(B)	(A)	MATERIAL NO.	種数 CKT.

REVISED	EC NO: J2010-2474 DRWN: YUHASEGAWA 2010/06/08 CHKD: K. TOYODA 2010/06/08 APPR: KMORIKAWA 2010/06/09	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
			10 UNDER	±0.2	DRAWN BY	DATE	TITLE EMBOSSD TAPE PACKAGE FOR 52271-**-29 -LEAD FREE-					
			10 OVER 30 UNDER	±0.25	CHECKED BY	DATE	MOLEX INCORPORATED					
			30 OVER	±0.3	APPROVED BY	DATE	MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
			ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-52271-039		2 OF 4	
G	REV			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



44	49.4	45.4	31	27.4	34.35	52271-2769	27		
			29	25.4	32.35	52271-2569	25		
			28	24.4	31.35	52271-2469	24		
			26	22.4	29.35	52271-2269	22		
			25	21.4	28.35	52271-2169	21		
			24	20.4	27.35	52271-2069	20		
			23	19.4	26.35	52271-1969	19		
			22	18.4	25.35	52271-1869	18		
			21	17.4	24.35	52271-1769	17		
キャリアテープ幅			F	D	(C)	(B)	(A)	MATERIAL NO.	極数

REVISED EC NO: J2010-2474 DRWN: YUHASEGAWA 2010/06/08 CHK'D: K. TOYODA 2010/06/08 APPR: KMORIKAWA 2010/06/09	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY M.UMEDA	DATE 2005/03/08	TITLE EMBOSSD TAPE PACKAGE FOR 52271-**29 -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY K.TOYODA	DATE 2005/03/08	MOLEX INCORPORATED			
	30 OVER	±0.3	APPROVED BY N.UKITA	DATE 2005/03/08	DOCUMENT NO. SD-52271-039			
	ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SHEET NO. 3 OF 4			



56	61.4	57.4	34	30.4	37.35	52271-3069	30
			32	28.4	35.35	52271-2869	28
キャリアテープ幅 CARRIER TAPE WIDTH			F	D	(C)	(B)	(A)
						MATERIAL NO.	種数 CKT.

REVISED EC NO: J2010-2474 DRWN: YUHASEGAWA 2010/06/08 CHKD: K. TOYODA 2010/06/08 APPR: KMORIKAWA 2010/06/09	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M.UMEDA	DATE 2005/03/08	TITLE EMBOSSD TAPE PACKAGE FOR 52271-**29 -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY K.TOYODA	DATE 2005/03/08	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY N.UKITA	DATE 2005/03/08	DOCUMENT NO. SD-52271-039		
	ANGULAR ±3 °		MATERIAL NO. SEE TABLE		SHEET NO. 4 OF 4		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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Факс: 8 (812) 320-02-42

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Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.